



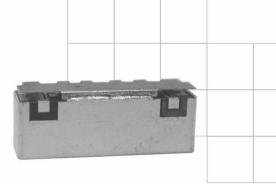
Band N79 USB Series TDD Bandpass Filter

Features

- Low Loss with High Rejection
- Low ripple
- Universal footprint across family for all TDD bands

Applications

- Wireless Infrastructure applications
- High-performance carrier-grade single-band TDD Pico-cell basestations for up to 5.0W at the antenna port.



Part Dimensions: 25.9 × 4.2 × 6.7 mm • 1.7 g

Materials: Ag plated ceramic block with tin plated brass shield

Description

Surface mount ceramic bandpass filter supports a universal footprint across all TDD frequency bands enabling the use of a common system PCB. Superior rejection, insertion loss, reliability, as well as both peak and average power handling compared to other bandpass filter technologies.

Electrical Specifications

Parameter	Frequency (MHz)	Typical at 25°C	Spec. at 25°C	Spec. over -40°C to +85°C
Nominal Impedance	-	50 ohms	-	-
Average Input Power	-	-	-	8.0 Watt max
Peak Input Power	-	-	-	80 Watt max
Input-Output Response				
Passband Insertion Loss (5 MHz avg)	4400 - 5000	1.2 dB	1.5 dB	1.6 dB max
Passband Ripple	4400 - 5000	0.5 dB	0.9 dB	1.0 dB max
Passband Return Loss	4400 - 5000	13 dB	12 dB	12 dB min
Attenuation:	1 - 3800	55 dB	40 dB	40 dB min
	5150 - 7200	46.5 dB	45 dB	45 dB min

Note: CTS tests each unit to the critical specifications above. Subsequent audits may deviate due to repeatability among different test systems which shall not exceed these allowances.

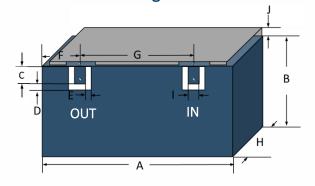
Specification Allowance				
Insertion Loss	0.1 dB			
Return Loss	1.0 dB			
Attenuation	1.0 dB			

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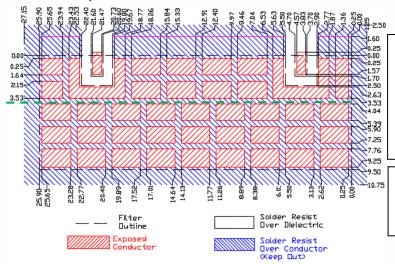
Mechanical Drawing



PCB Layout

44.0 mm

4.20 mm



Dim.	Nominal (mm)	Tolerance (±mm or Max)
Α	25.90	max
В	2.90	max
С	1.70	0.13
D	0.80	0.13
Е	0.80	0.13
F	4.20	0.13
G	16.90	0.13
Н	6.70	max
1	1.00	0.13
J	1.10	0.20

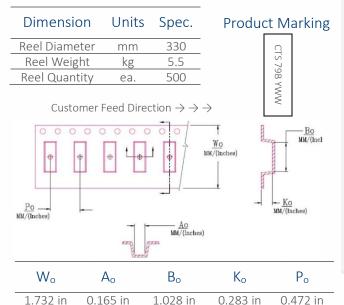
IMPORTANT: Please assure >=30mils (0.75mm) thickness of dielectric beneath the I/O Pads \underline{and} the surrounding clearance zone down to the ground plane.

Please assure sufficient ground vias between the top metal ground plane and the primary ground plane.

Recommended solder: 4-6 mils of SAC305 with reflow including 120s of soak at 217°C, and up to 30 sec peak at 241°C.

NOTE: The width of 9.50mm is necessary to support frequencies as low as 1885MHz for Band 39. If only higher frequency TDD bands are supported, then a smaller space can be allocated on the layout.

Packaging and Marking



26.10 mm

7.20 mm

Electrical Response



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12.0 mm